

BigTwin SuperServer SYS-622BT-HNC8R

2U 4-Node BigTwin with 3 hot-swap 3.5" NVMe/SAS/SATA drives per node



Key Applications

Hyperconverged Infrastructure, Scale-Out File Storage, Back-up & Recovery,

Key Features

- Four **hot-pluggable** systems (nodes) in a 2U form factor. Each node supports the following;:
- Dual Socket E2 Intel® Xeon® 6700/6500 series processors with P-cores or 6700 processors with E-cores up to 150W with air cooling or 350W with liquid cooling
Single CPU configurations supported while maintaining all expansion slot functionality; see Option A for drive support limitations;
- Up to 16 DIMMs supporting up to 4TB DDR5-6400 in 1DPC;
- Flexible networking with OCP 3.0 AIOM slot;
- Up to 2 PCIe 5.0 x16 LP slots; Tool-less support
Internal PCIe 5.0 for 2 NVMe M.2 support onboard
Optional 4 NVMe M.2 support onboard with built-in HW RAID1 via SCC-A2NM2241GH-B1;
- Up to 3 front hot-swap 3.5" NVMe/SAS drive bays
Built-in SAS3 Support via Broadcom 3808; IT Mode;



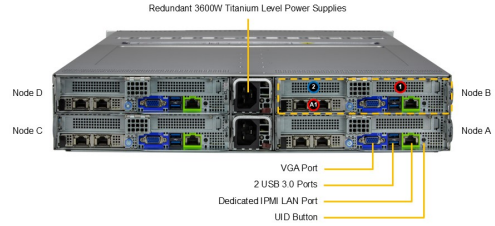
Form Factor	2U Rackmount Enclosure: 449 x 88 x 774mm (17.68" x 3.47" x 30.5") Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")
Processor	Dual Socket E2 (LGA-4710) Intel® Xeon® 6700/6500 series processors with P-cores or 6700 series processors with E-cores P-cores: Up to 128C/256T; Up to 108MB Cache per CPU E-cores: Up to 144C/144T; Up to 108MB Cache per CPU
System Memory	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 6400MT/s ECC DDR5 RDIMM
Drive Bays Configuration	Default: Total 3 bays <ul style="list-style-type: none"> • 2 front hot-swap 3.5" PCIe 5.0 NVMe/SAS drive bays • 1 front hot-swap 3.5" PCIe 4.0 NVMe/SAS drive bay Option A: Total 3 bays <ul style="list-style-type: none"> • 2 front hot-swap 3.5" PCIe 5.0 NVMe/SAS drive bays • 1 front hot-swap 3.5" SAS drive bay M.2: 2 M.2 PCIe 5.0 x4 NVMe slots (M-key 22110; VROC required for RAID)
Expansion Slots	Default <ul style="list-style-type: none"> • 2 PCIe 5.0 x16 LP slots • 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)
On-Board Devices	SAS: SAS (12Gbps) via Broadcom® 3808; (IT mode) Chipset: System on Chip Network Connectivity: Via AIOM
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port USB: 2 USB 3.0 Type-A ports(Rear) Video: 1 VGA port

(Front View – System)



Drive Bay (Node A-D)	Description
①-④	2 Hot-swap 3.5" PCIe 5.0 NVMe/SAS/SATA Drive Bays (from CPU1)
⑤	1 Hot-swap 3.5" PCIe 4.0 NVMe/SAS/SATA Drive Bay (from CPU2)

(Rear View – System)



Per Node (Node A-D)	Slot Description
①	PCIe 5.0 x8 LP
②	PCIe 5.0 x16 LP
③	PCIe 5.0 x16 AIDM

System Cooling	Fans: 4x 14.9K RPM Heavy Duty 80x80x38mm Fan(s) Air Shroud: 2 Air Shrouds Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)
Power Supply	2x 3600W Redundant (1 + 1) Titanium Level (96%) power supplies
System BIOS	BIOS Type: AMI 32MB SPI Flash
Management	SuperCloud Composer®; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors
Dimensions and Weight	Weight: Gross Weight: 96.6 lbs (43.8 kg) Net Weight: 66.1 lbs (30 kg) Available Color: Black front & silver body
Operating Environment	Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -30°C to 60°C (-22°F to 140°F) Operating Relative Humidity: 8% to 80% (non-condensing) Non-operating Relative Humidity: 8% to 90% (non-condensing)
Motherboard	Super X14DBT-B
Chassis	CSE-827BQ2-R3K60P